123-02

REWORKABLE POLYIMIDE BASED DIE ATTACH ADHESIVE

DESCRIPTION: 123-02 is a silver loaded, reworkable, electrically conductive adhesive. This product features excellent adhesion to Kapton, Mylar, FR4 board, glass and a variety of other substrates. This product can be reworked at temperatures as low as 180°C. Some applications for 123-02 include, but are not limited to, MCM-C, L or D, PPGA, PBGA, Flip Chip/KGD and solder replacement on PC boards. 123-02 is also useful for attaching large expansion mismatched components. 123-02 may be applied by syringe dispensing, screen-printing and stenciling techniques.

TYPICAL PROPERTIES:

- Viscosity (cps) 25,000-50,000
- Filler Silver
- % Filler (cured) 90 min.
- Volume Resistance, max. (Ω-cm) 0.00008
- Sheet Resistivity, max. (Ω/sq./mil) 0.03
- Solderable No
- Thermal conductivity (W/mk) 2.5
- Useful Temperature Range (°C) -55 to 180
- Thermal Stability (°C) Good to 220

SUGGESTED HANDLING & CURING: 123-02 is ready to use as supplied. Further thinning may be accomplished by adding small amounts of CMI Thinner #203. Prior to using, be certain to resuspend silver. Best properties, for most applications, result when cured for 10 minutes at 180°C. Good properties are obtained on a variety of substrates by curing at temperatures ranging from 50°C to 200°C. End user is advised to experimentally determine temperature and time best suited for individual applications.

STORAGE: Shelf life: 3 months at 25°C; or 6 months at 5°C; or 9 months at -10°C.

SAFETY & HANDLING: Use with adequate ventilation. Keep away from sparks and open flames. Avoid prolonged contact with skin and breathing of vapors. Wash with soap and water to remove from skin.

All technical information is based on data obtained by CMI personnel and is believed to be reliable. No warranty is either expressed or implied with respect to results or possible infringements on patents.

REVISION DATE: 3/3/03 REVISION: A